

## HIGH-SPEED 3.3V 128K x9/x8 SYNCHRONOUS PIPELINED DUAL-PORT STATIC RAM

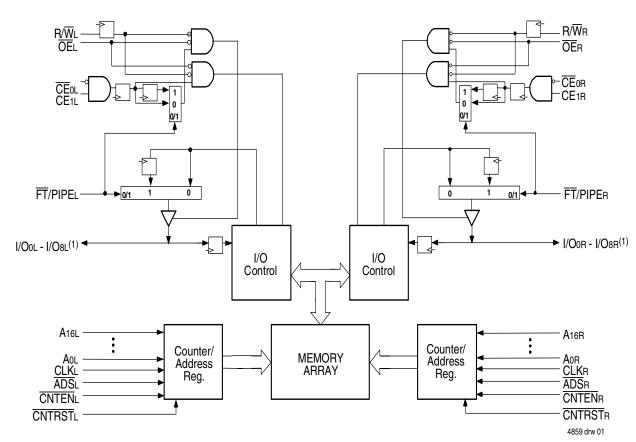
### IDT70V9199/099L

### Features:

- True Dual-Ported memory cells which allow simultaneous access of the same memory location
- High-speed clock to data access
  - Commercial: 9/12ns (max.)
  - Industrial: 9ns (max.)
- Low-power operation
  - IDT70V9199/099L
    - Active: 500mW (typ.)
    - Standby: 1.5mW (typ.)
- ◆ Flow-Through or Pipelined output mode on either port via the FT/PIPE pins
- Dual chip enables allow for depth expansion without additional logic

- Counter enable and reset features
- Full synchronous operation on both ports
  - 4ns setup to clock and 1ns hold on all control, data, and address inputs
  - Data input, address, and control registers
  - Fast 9 ns clock to data out in the Pipelined output mode
  - Self-timed write allows fast cycle time
  - 15ns cycle time, 66 MHz operation in Pipelined output mode
- LVTTL- compatible, single 3.3V (±0.3V) power supply
- Industrial temperature range (-40°C to +85°C) is available for selected speeds
- Available in a 100-pin Thin Quad Flatpack (TQFP)
- Green parts available, see ordering information

## Functional Block Diagram



### NOTE:

1. I/O<sub>0</sub>x - I/O<sub>7</sub>x for IDT70V9099.

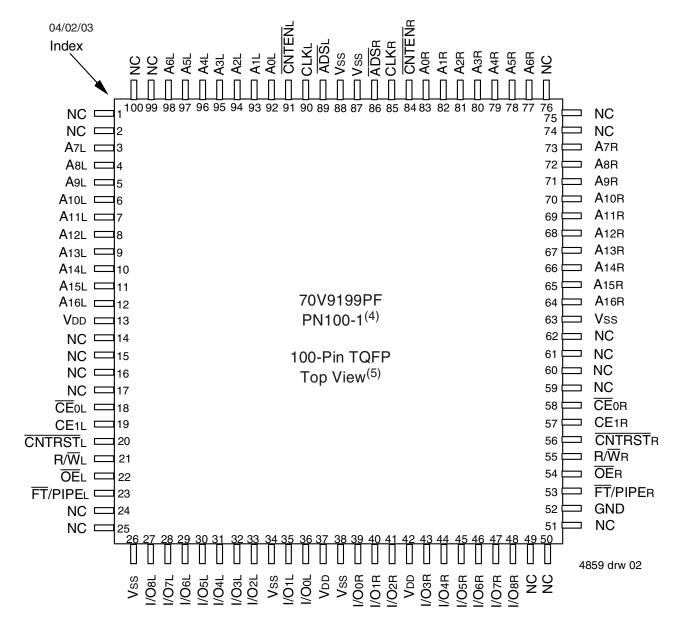
JULY 2010

### Description:

The IDT70V9199/099 is a high-speed128K x9/x8 bit synchronous Dual-Port RAM. The memory array utilizes Dual-Port memory cells to allow simultaneous access of any address from both ports. Registers on control, data, and address inputs provide minimal setup and hold times. The timing latitude provided by this approach allows systems to be designed with very short cycle times.

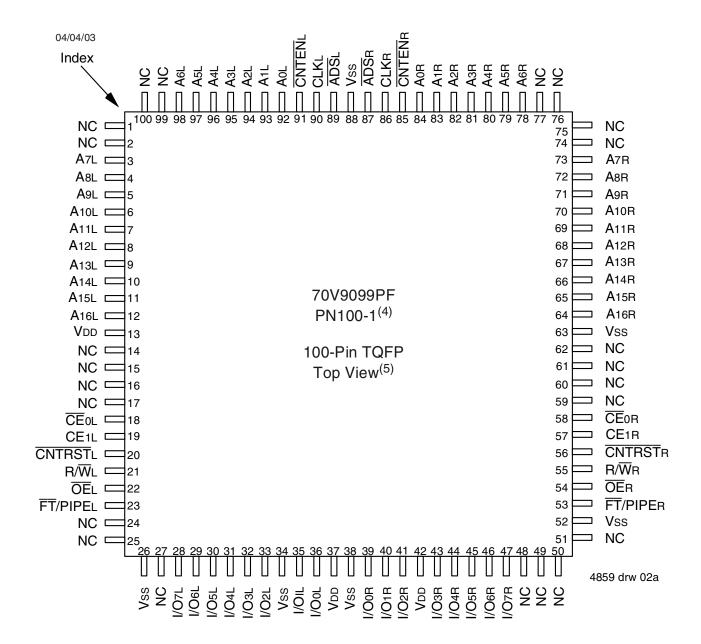
With an input data register, the IDT70V9199/099 has been optimized for applications having unidirectional or bidirectional data flow in bursts. An automatic power down feature, controlled by  $\overline{\text{CE}}$ 0 and CE1, permits the on-chip circuitry of each port to enter a very low standby power mode. Fabricated using IDT's CMOS high-performance technology, these devices typically operate on only 500mW of power.

## Pin Configuration<sup>(1,2,3)</sup>



- 1. All VDD pins must be connected to power supply.
- 2. All Vss pins must be connected to ground supply.
- 3. Package body is approximately 14mm x 14mm x 1.4mm.
- 4. This package code is used to reference the package diagram.
- 5. This text does not indicate orientation of the actual part-marking.

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### Pin Names

Left Port	eft Port Right Port Names			
CEOL, CE1L	CE0R, CE1R	Chip Enables		
R/WL	R/WR	Read/Write Enable		
ŌĒL	<del>OE</del> R	Output Enable		
A0L - A16L	AOR - A16R	Address		
I/O0L - I/O8L <sup>(1)</sup>	I/Oor - I/O8R <sup>(1)</sup>	Data Input/Output		
CLKL	CLKR	Clock		
ADSL	<del>ADS</del> R	Address Strobe Enable		
CNTENL	<u>CNTEN</u> R	Counter Enable		
CNTRSTL	<u>CNTRST</u> R	Counter Reset		
FT/PIPEL	FT/PIPER	Flow-Through / Pipeline		
V	DD	Power (3.3V)		
V	SS	Ground (0V)		

NOTE:

1. I/Oox - I/O7x for IDT70V9099.

4859 tbl 01

# <u>Truth Table I—Read/Write</u> and Enable Control<sup>(1,2,3)</sup>

ŌĒ	CLK	Œ0	CE1	R/W	I/O <sub>0-8</sub> <sup>(4)</sup>	MODE			
Х	1	Н	Х	Х	High-Z	Deselected-Power Down			
Х	1	Χ	L	Х	High-Z	Z Deselected–Power Down			
Х	1	L	Н	L	DATAIN	Write			
L	1	L	Н	Н	DATAout	Read			
Н	Х	L	Н	Х	High-Z	Outputs Disabled			

### NOTES:

- 1. "H" =  $V_{IH}$ , "L" =  $V_{IL}$ , "X" = Don't Care.
- 2. ADS, CNTEN, CNTRST = X.
- 3.  $\overline{\text{OE}}$  is an asynchronous input signal.
- 4. I/O<sub>0</sub> I/O<sub>7</sub> for IDT70V9099.

## Truth Table II—Address Counter Control<sup>(1,2)</sup>

External Address	Previous Internal Address	Internal Address Used	CLK	ĀDS	CNTEN	CNTRST	I/O <sup>(3)</sup>	MODE
Х	Х	0	1	Х	Х	L <sup>(4)</sup>	Di/o(0)	Counter Reset to Address 0
An	Х	An	1	L <sup>(4)</sup>	Х	Н	Di/o(n)	External Address Loaded into Counter
An	Ар	Ар	1	Н	Н	Н	Dvo(p)	External Address Blocked—Counter disabled (Ap reused)
Х	Ар	Ap + 1	1	Н	L <sup>(5)</sup>	Н	D⊮o(p+1)	Counter Enabled—Internal Address generation

4859 tbl 03

4859 tbl 02

- 1. "H" =  $V_{IH}$ , "L" =  $V_{IL}$ , "X" = Don't Care.
- 2.  $\overline{CE}_0$  and  $\overline{OE} = V_{IL}$ ; CE1 and  $R/\overline{W} = V_{IH}$ .
- 3. Outputs configured in Flow-Through Output mode; if outputs are in Pipelined mode the data out will be delayed by one cycle.
- 4. ADS and CNTRST are independent of all other signals including CEo and CE1.
- 5. The address counter advances if CNTEN = VIL on the rising edge of CLK, regardless of all other signals including CEo and CE1.

## Recommended Operating Temperature and Supply Voltage<sup>(1)</sup>

Grade	Ambient Temperature <sup>(2)</sup>	GND	VDD
Commercial	0°C to +70°C	0V	3.3V <u>+</u> 0.3V
Industrial	-40°C to +85°C	0V	3.3V <u>+</u> 0.3V

#### NOTES

4859 tbl 04

1. This is the parameter Ta. This is the "instant on" case temperature.

# Recommended DC Operating Conditions

Symbol	Parameter	Min.	Тур.	Max.	Unit
VDD	Supply Voltage	3.0	3.3	3.6	V
Vss	Ground	0	0	0	V
VIH	Input High Voltage	2.0	_	VDD+0.3V <sup>(2)</sup>	V
VIL	Input Low Voltage	-0.3 <sup>(1)</sup>		0.8	V

### NOTES:

4859 tbl 05

- 1.  $V_{IL} \ge -1.5V$  for pulse width less than 10 ns.
- 2. VTERM must not exceed VDD +0.3V.

## Absolute Maximum Ratings(1)

Symbol	Rating Commercial & Industrial		Unit
VTERM <sup>(2)</sup>	Terminal Voltage with Respect to GND	-0.5 to +4.6	>
TBIAS <sup>(3)</sup>	Temperature Under Bias	-55 to +125	°C
Tstg	Storage Temperature	-65 to +150	°C
NLT	Junction Temperature	+150	۰C
Іоит	DC Output Current	50	mA

### NOTES:

4859 tbl 06

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- 2. VTERM must not exceed VDD +0.3V for more than 25% of the cycle time or 10ns maximum, and is limited to  $\leq$  20mA for the period of VTERM  $\geq$  VDD + 0.3V.
- 3. Ambient Temperature Under DC Bias. No AC Conditions. Chip deselect.

## Capacitance<sup>(1)</sup>

 $(TA = +25^{\circ}C, f = 1.0MHz)$ 

Symbol	Parameter	Conditions <sup>(2)</sup>	Max.	Unit
CIN	Input Capacitance	VIN = 3dV	9	pF
Соит <sup>(3)</sup>	Output Capacitance	Vout = 3dV	10	pF

#### NOTES:

4859 tbl 07

- These parameters are determined by device characterization, but are not production tested.
- 3dV references the interpolated capacitance when the input and output switch from 0V to 3V or from 3V to 0V.
- 3. Cout also references CI/O.

# DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range (VDD = 3.3V ± 0.3V)

			70V9199/099L		
Symbol	Parameter	Test Conditions	Min.	Max.	Unit
Lu	Input Leakage Current <sup>(1)</sup>	$V_{DD} = 3.6V$ , $V_{IN} = 0V$ to $V_{DD}$	_	5	μA
ILO	Output Leakage Current	$\overline{\text{CE}}$ = ViH or CE1 = ViL, VouT = 0V to VDD	-	5	μΑ
Vol	Output Low Voltage	IoL = +4mA		0.4	V
Voh	Output High Voltage	IOH = -4mA	2.4	_	V

### NOTE

4859 tbl 08

1. At  $VDD \le 2.0V$  input leakages are undefined.

# DC Electrical Characteristics Over the Operating Temperature Supply Voltage Range<sup>(3)</sup> (VDD = 3.3V ± 0.3V)

					70V9199/099L9 Com'l & Ind			70V9199 Com'l	
Symbol	Parameter	Test Condition	Versio	n	Typ. <sup>(4)</sup>	Max.	Typ. <sup>(4)</sup>	Max.	Unit
IDD	Dynamic Operating Current (Both	CEL and CER= VIL,	COM'L	L	175	230	150	200	mA
	Ports Active)	Outputs Disabled, f = fMAX <sup>(1)</sup>	IND	L	180	240	_	_	
ISB1	Standby Current	CEL = CER = VIH	COM'L	L	40	65	30	50	mA
	(Both Ports - TTL Level Inputs)	$f = fMAX^{(1)}$	IND	L	50	70	_	_	
ISB2	Standby			L	110	145	95	130	mA
	Current (One $\overline{CE}$ "B" = VIH <sup>(5)</sup>	Active Port Outputs Disabled,	IND	L	110	155	_	_	
ISB3	Full Standby	Both Ports CEL and	COM'L	L	0.4	2	0.4	2	mA
Current (Both Ports - CMOS Level Inputs)	Ports - CMOS	$\overline{\text{CER}} \ge \text{VDD} - 0.2\text{V},$ $\overline{\text{VIN}} \ge \overline{\text{VDD}} - 0.2\text{V} \text{ or}$ $\overline{\text{VIN}} \le 0.2\text{V}, f = 0^{(2)}$	IND	L	0.4	2		_	
ISB4	Full Standby <u>CE</u> "A" ≤ 0.2V and		COM'L	L	100	140	90	125	mA
Current (One Port - CMOS Level Inputs)	$\overline{\text{CE}}^*\text{B}^* \stackrel{\sum}{=} \text{VDD} - 0.2\text{V}^{(5)}$ $\text{Vin} \geq \text{VDD} - 0.2\text{V or}$ $\text{Vin} \leq 0.2\text{V}$ , Active Port, Outputs Disabled, $f = \text{fmAX}^{(1)}$	IND	L	100	155	_	_		

4859 tbl 09

- 1. At f = fmax, address and control lines (except Output Enable) are cycling at the maximum frequency clock cycle of 1/tcyc, using "AC TEST CONDITIONS" at input levels of GND to 3V.
- 2. f = 0 means no address, clock, or control lines change. Applies only to input at CMOS level standby.
- 3. Port "A" may be either left or right port. Port "B" is the opposite from port "A".
- 4. VDD = 3.3V,  $TA = 25^{\circ}C$  for Typ, and are not production tested. IDD DC(f=0) = 90mA (Typ). 5.  $\overline{CE}x = VIL means \overline{CE}0x = VIL and CE1x = VIH$
- - $\overline{CE}x = V_{IH} \text{ means } \overline{CE}_{0X} = V_{IH} \text{ or } CE_{1X} = V_{IL}$

  - $\label{eq:control_control} \begin{array}{l} \overline{CE}x \leq 0.2V \text{ means } \overline{CE}ox \leq 0.2V \text{ and } CE_{1}x \geq V_{DD} 0.2V \\ \overline{CE}x \geq V_{DD} 0.2V \text{ means } \overline{CE}ox \geq V_{DD} 0.2V \text{ or } CE_{1}x \leq 0.2V \\ \end{array}$
  - "X" represents "L" for left port or "R" for right port.

## **AC Test Conditions**

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	3ns Max.
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
Output Load	Figures 1, 2, and 3

4859 tbl 10

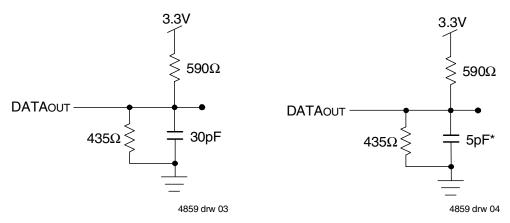


Figure 1. AC Output Test load.

Figure 2. Output Test Load (For tckLz, tckHz, toLz, and toHz).
\*Including scope and jig.

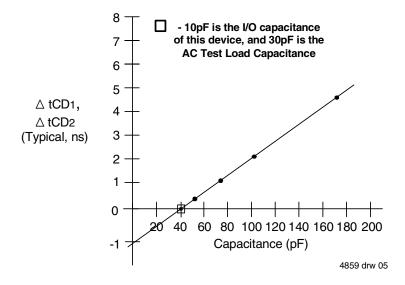


Figure 3. Typical Output Derating (Lumped Capacitive Load).

# AC Electrical Characteristics Over the Operating Temperature Range (Read and Write Cycle Timing) $^{(3)}$ (VDD = 3.3V ± 0.3V)

			9/099L9 & Ind	70V919 Com'	9/099L12 I Only	
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit
tcyc1	Clock Cycle Time (Flow-Through) <sup>(2)</sup>	25		30	_	ns
tcyc2	Clock Cycle Time (Pipelined) <sup>(2)</sup>	15		20	_	ns
tcH1	Clock High Time (Flow-Through) <sup>(2)</sup>	12		12		ns
tCL1	Clock Low Time (Flow-Through) <sup>(2)</sup>	12		12		ns
tCH2	Clock High Time (Pipelined) <sup>(2)</sup>	6		8		ns
tCL2	Clock Low Time (Pipelined) <sup>(2)</sup>	6		8	_	ns
tr	Clock Rise Time	_	3		3	ns
tF	Clock Fall Time	_	3		3	ns
tsa	Address Setup Time	4		4		ns
tha	Address Hold Time	1		1		ns
tsc	Chip Enable Setup Time	4		4		ns
tHC	Chip Enable Hold Time	1		1		ns
tsw	R/W Setup Time	4		4		ns
tHW	R/W Hold Time	1		1		ns
tsd	Input Data Setup Time	4		4		ns
thd	Input Data Hold Time	1		1		ns
tsad	ADS Setup Time	4		4		ns
thad	ADS Hold Time	1		1		ns
tscn	CNTEN Setup Time	4		4	_	ns
thcn	CNTEN Hold Time	1		1	_	ns
tsrst	CNTRST Setup Time	4		4	_	ns
thrst	CNTRST Hold Time	1		1		ns
toe	Output Enable to Data Valid		9		12	ns
tolz	Output Enable to Output Low-Z <sup>(1)</sup>	2		2		ns
tонz	Output Enable to Output High-Z <sup>(1)</sup>	1	7	1	7	ns
tCD1	Clock to Data Valid (Flow-Through) <sup>(2)</sup>		20		25	ns
tCD2	Clock to Data Valid (Pipelined) <sup>(2)</sup>		9		12	ns
toc	Data Output Hold After Clock High	2		2	_	ns
tckhz	Clock High to Output High-Z <sup>(1)</sup>	2	9	2	9	ns
tcklz	Clock High to Output Low-Z <sup>(1)</sup>	2		2	_	ns
Port-to-Port I	Delay	•				
tcwdd	Write Port Clock High to Read Data Delay		35		40	ns
tccs	Clock-to-Clock Setup Time		15		15	ns

NOTES

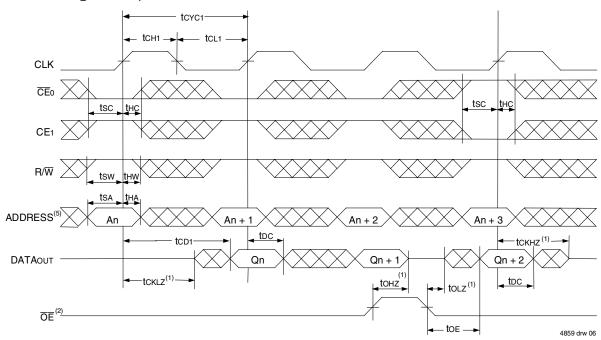
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Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2). This parameter is guaranteed characterization, but is not production tested.

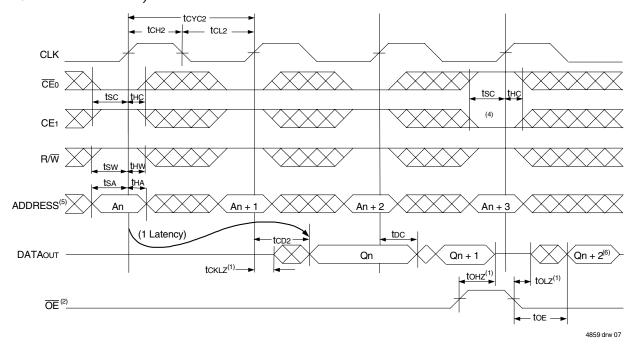
<sup>2.</sup> The Pipelined output parameters (tcyc2, tcb2) apply to either or both the Left and Right ports when FT/PIPE = VIH. Flow-through parameters (tcyc1, tcb1) apply when FT/PIPE = VIL for that port.

<sup>3.</sup> All input signals are synchronous with respect to the clock except for the asynchronous Output Enable (OE), FT/PIPER, and FT/PIPEL.

# Timing Waveform of Read Cycle for Flow-Through Output $(\overline{FT}/PIPE"x" = VIL)^{(3,6)}$

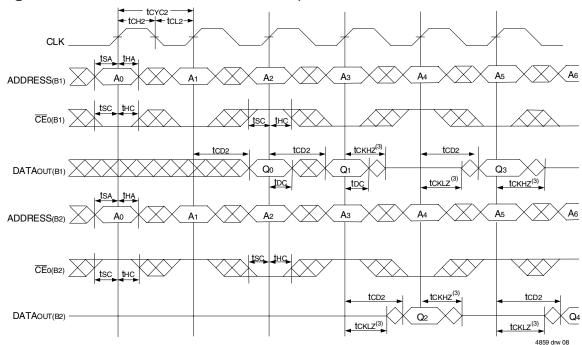


# Timing Waveform of Read Cycle for Pipelined Operation $(\overline{FT}/PIPE"x" = VIH)^{(3,6)}$

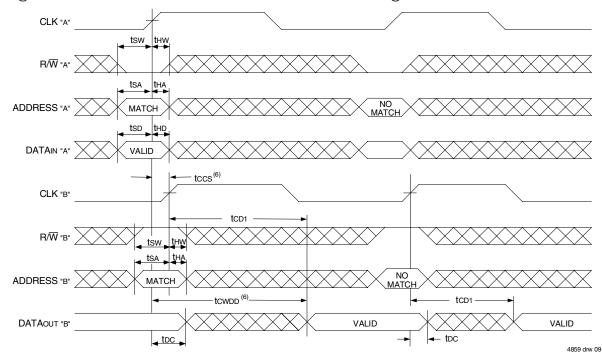


- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2.  $\overline{\text{OE}}$  is asynchronously controlled; all other inputs are synchronous to the rising clock edge.
- 3.  $\overline{ADS} = VIL \text{ and } \overline{CNTRST} = VIH.$
- 4. The output is disabled (High-Impedance state) by  $\overline{\text{CE}}_0 = \text{V}_{\text{IH}}$  or CE1 = V<sub>IL</sub> following the next rising edge of the clock. Refer to Truth Table 1.
- 5. Addresses do not have to be accessed sequentially since ADS = VIL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 6. 'X' here denotes Left or Right port. The diagram is with respect to that port.

# Timing Waveform of a Bank Select Pipelined Read (1,2)



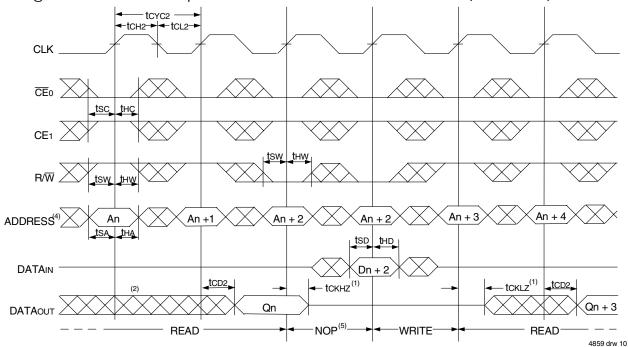
# Timing Waveform with Port-to-Port Flow-Through Read<sup>(4,5,7)</sup>



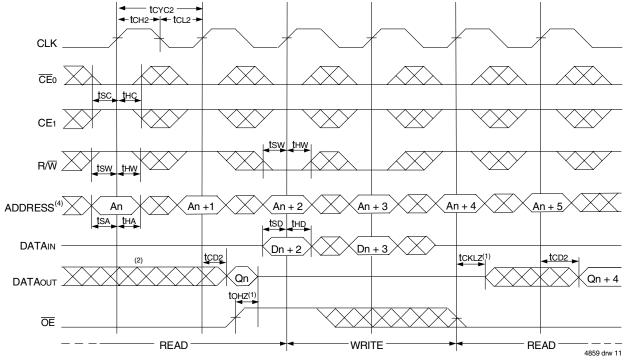
- 1. B1 Represents Bank #1; B2 Represents Bank #2. Each Bank consists of one IDT70V9199/099 for this waveform, and are setup for depth expansion in this example. ADDRESS(B1) = ADDRESS(B2) in this situation.
- 2.  $\overline{\text{OE}}$  and  $\overline{\text{ADS}}$  = Vil.; CE1(B1), CE1(B2), R/ $\overline{\text{W}}$  and  $\overline{\text{CNTRST}}$  = ViH.
- 3. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 4.  $\overline{\text{CE}}_0$  and  $\overline{\text{ADS}} = \text{Vii.}$ ; CE1 and  $\overline{\text{CNTRST}} = \text{Viii.}$
- 5.  $\overline{OE}$  = VIL for the Right Port, which is being read from.  $\overline{OE}$  = VIH for the Left Port, which is being written to.
- 6. If tccs ≤ maximum specified, then data from right port READ is not valid until the maximum specified for tcwpb.

  If tccs > maximum specified, then data from right port READ is not valid until tccs + tcp1. tcwpb does not apply in this case.
- 7. All timing is the same for both Left and Right ports. Port "A" may be either Left or Right port. Port "B" is the opposite from Port "A".

# Timing Waveform of Pipelined Read-to-Write-to-Read (**OE** = VIL)(3)

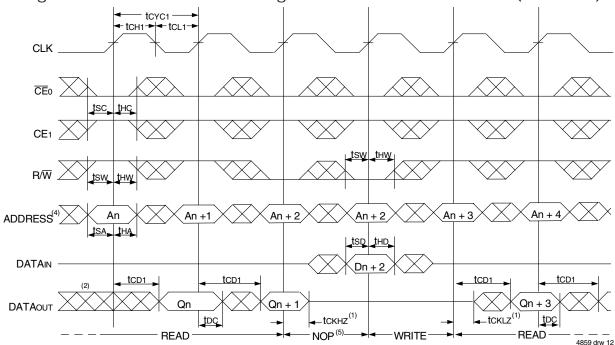


# Timing Waveform of Pipelined Read-to-Write-to-Read (**OE** Controlled)(3)

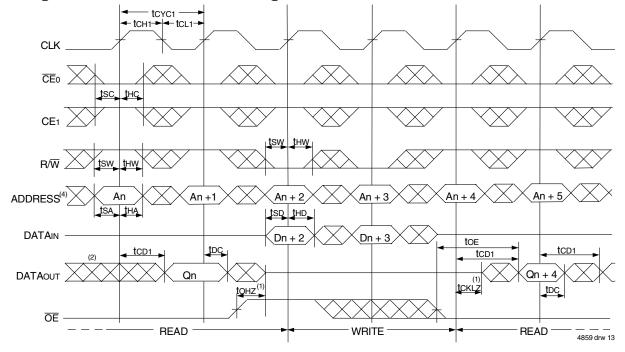


- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- 3.  $\overline{CE}_0$  and  $\overline{ADS} = VIL$ ; CE1 and  $\overline{CNTRST} = VIH$ . "NOP" is "No Operation".
- 4. Addresses do not have to be accessed sequentially since ADS = VIL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be re-written to guarantee data integrity.

# Timing Waveform of Flow-Through Read-to-Write-to-Read (**OE** = VIL)<sup>(3)</sup>

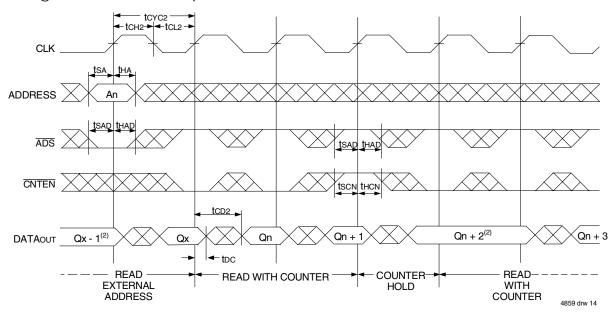


# Timing Waveform of Flow-Through Read-to-Write-to-Read (**OE** Controlled)<sup>(3)</sup>

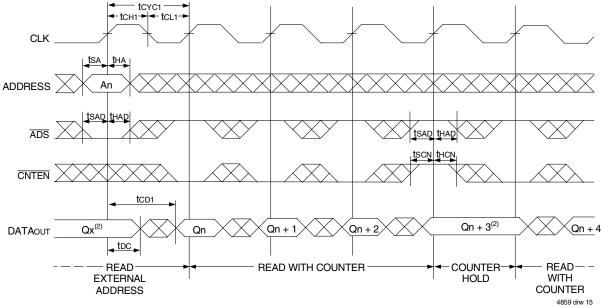


- 1. Transition is measured 0mV from Low or High-impedance voltage with the Output Test Load (Figure 2).
- 2. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- 3.  $\overline{CE_0}$  and  $\overline{ADS}$  = V<sub>IL</sub>; CE<sub>1</sub> and  $\overline{CNTRST}$  = V<sub>IH</sub>. "NOP" is "No Operation".
- 4. Addresses do not have to be accessed sequentially since  $\overline{ADS}$  = V<sub>IL</sub> constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be re-written to guarantee data integrity.

# Timing Waveform of Pipelined Read with Address Counter Advance<sup>(1)</sup>

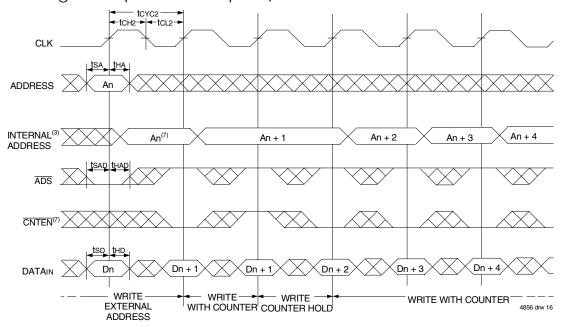


# Timing Waveform of Flow-Through Read with Address Counter Advance<sup>(1)</sup>

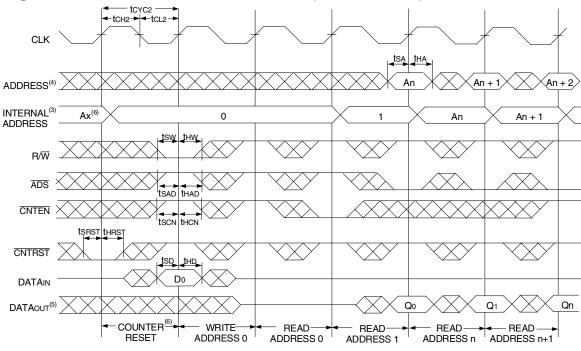


- 1.  $\overline{\text{CE}}_0$  and  $\overline{\text{OE}}$  = VIL; CE1, R/ $\overline{\text{W}}$ , and  $\overline{\text{CNTRST}}$  = VIH.
- 2. If there is no address change via  $\overline{ADS} = VIL$  (loading a new address) or  $\overline{CNTEN} = VIL$  (advancing the address), i.e.  $\overline{ADS} = VIH$  and  $\overline{CNTEN} = VIH$ , then the data output remains constant for subsequent clocks.

# Timing Waveform of Write with Address Counter Advance (Flow-Through or Pipelined Outputs)<sup>(1)</sup>



# Timing Waveform of Counter Reset (Pipelined Outputs)(2)



# **NOTES:**1. $\overline{CE}_0$ and $R/\overline{W} = V_{IL}$ ; $CE_1$ and $\overline{CNTRST} = V_{IH}$ .

- 2.  $\overline{CE}_0 = V_{IL}$ ; CE<sub>1</sub> = V<sub>IH</sub>.
- 3. The "Internal Address" is equal to the "External Address" when  $\overline{ADS} = VIL$  and equals the counter output when  $\overline{ADS} = VIH$ .
- 4. Addresses do not have to be accessed sequentially since  $\overline{ADS} = V_{1L}$  constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
- 5. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
- 6. No dead cycle exists during counter reset. A READ or WRITE cycle may be coincidental with the counter reset cycle. ADDRo will be accessed. Extra cycles are shown here simply for clarification.
- CNTEN = VIL advances Internal Address from 'An' to 'An +1'. The transition shown indicates the time required for the counter to advance.
   The 'An +1' Address is written to during this cycle.

## **Functional Description**

The IDT70V9199/099 provides a true synchronous Dual-Port Static RAM interface. Registered inputs provide minimal set-up and hold times on address, data, and all critical control inputs. All internal registers are clocked on the rising edge of the clock signal, however, the self-timed internal write pulse is independent of the LOW to HIGH transition of the clock signal.

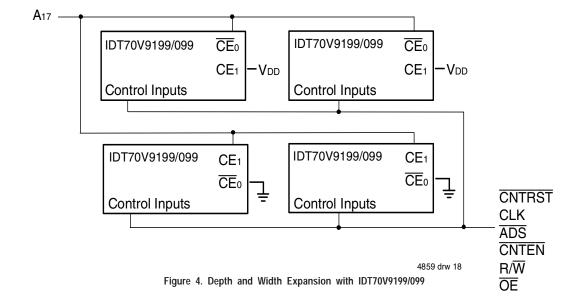
An asynchronous output enable is provided to ease asynchronous bus interfacing. Counter enable inputs are also provided to staff the operation of the address counters for fast interleaved memory applications.

 $\overline{\text{CE}}_0 = \text{VIL}$  and  $\text{CE}_1 = \text{VIH}$  for one clock cycle will power down the internal circuitry to reduce static power consumption. Multiple chip enables allow easier banking of multiple IDT70V9199/099's for depth expansion configurations. When the Pipelined output mode is enabled, two cycles are required with  $\overline{\text{CE}}_0 = \text{VIH}$  or  $\text{CE}_1 = \text{VIL}$  to re-activate the outputs.

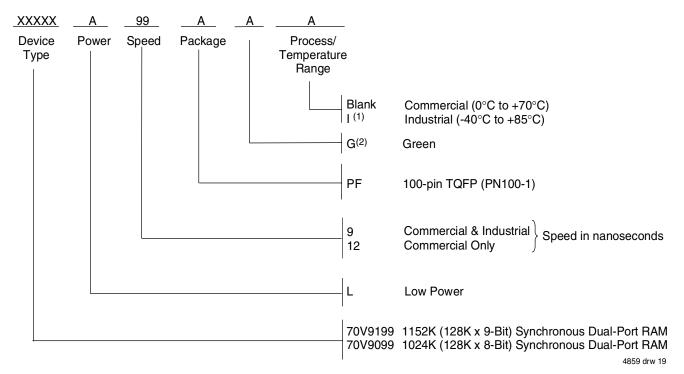
## Depth and Width Expansion

The IDT70V9199/099 features dual chip enables (refer to Truth Table I) in order to facilitate rapid and simple depth expansion with no requirements for external logic. Figure 4 illustrates how to control the various chip enables in order to expand two devices in depth.

The IDT70V9199/099 can also be used in applications requiring expanded width, as indicated in Figure 4. Since the banks are allocated at the discretion of the user, the external controller can be set up to drive the input signals for the various devices as required to allow for 18/16-bit or wider applications.



## Ordering Information



#### NOTES

- 1. Industrial temperature range is available. For specific speeds, packages and powers contact your sales office.
- 2. Green parts available. For specific speeds, packages and powers contact your local sales office.

## IDT Clock Solution for IDT70V9199/099 Dual-Port

IDT Dual-Port Part Number	Dual-Port I/O Specitications			Dual-Port Clock S	IDT	IDT		
	Voltage	I/O	Input Capacitance	Input Duty Cycle Requirement  Maximum Frequency		Jitter Tolerance	PLL Clock Devices	Non-PLL Clock Devices
70V9199/099	3.3	LVTTL	9pF	40%	100	150ps	IDT2305 IDT2308 IDT2309	FCT3805 FCT3805D/E FCT3807 FCT3807D/E

4859 tbl12

## **Datasheet Document History**

09/30/99: Initial Public Release 11/12/99: Replaced IDT logo

01/10/01: Page 3 Changed information in Truth Table II
Page 4 Increased storage temperature parameters

Clarified TA parameter

Page 5 DC Electrical parameters–changed wording from "open" to "disabled"

Changed ±200mV to 0mV in notes Removed Preliminary status

04/09/03: Consolidate multiple devices into one datasheet

Changed naming conventions from Vcc to Vdd and from GND to Vss

Pages 2 & 3 Added date revision to pin configurations

Page 5 Added junction temperature to Absolute Maximum Ratings Table

Added Ambient Temperature footnote

Pages 1, 6 & 16 Added 6ns speed grade

Page 6 Added updated DC power numbers to the DC Electrical Characteristics Table

Page 8 Added 6ns speed AC timing numbers and changed to E to be equal to tcp2 in the AC Electrical

CharacteristicsTable

Page 16 Added IDT Clock Solution Table
Page 1 Added green availability to features

01/10/06: Page 1 Added green availability to features
Page 16 Added green indicator to ordering information

02/22/07: Page 1 Removed 6ns & 7ns speed grades from features
Page 6 Removed 6ns & 7ns speed grade values from the DC Electrical Characteristics Table

Page 8 Removed 6ns & 7ns speed grade values from the AC Electrical Characteristics Table

Page 16 Removed 6ns & 7ns speed grades from ordering information

01/19/09: Page 16 Removed "IDT" from orderable part number

07/26/10: Page 8 In order to correct the header notes of the AC Elect Chars Table and align them with the Industrial temp range

values located in the table, the commercial TA header note has been removed

Pages 9-12 In order to correct the footnotes of timing diagrams, CNTEN has been removed to reconcile the footnotes with

the CNTEN logic definition found in Truth Table II - Address Counter Control



# **Mouser Electronics**

**Authorized Distributor** 

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## IDT (Integrated Device Technology):

 70V9199L7PFG
 70V9199L7PFG8
 70V9099L12PF
 70V9199L12PF
 70V9099L6PF8
 70V9099L9PFI
 70V9199L9PFI
 70V9099L6PFI
 70V909PI
 70V909PI
 70V909PI